

7th April 2011

## Mitsubishi Power Device Announcement – Japanese Earthquake

Dear valued customers,

We would like to inform you of the latest situation of Mitsubishi Power Semiconductor production following the recent earthquake and tsunami in Japan as follows.

### **1. Influence for production May onwards (At latest)**

We have been confirming each supplier (material and raw material) situation and negotiating delivery pull-in with them. As a result at latest, we will inform update situation as follows.

\*It is average value and some parts are worse than the average.

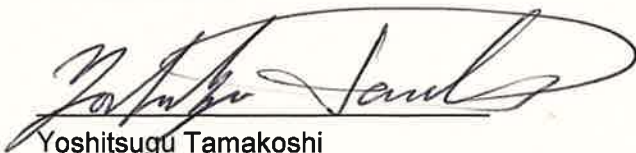
\*It is estimation as of today, situation below may change by unexpected accident.

(It is not included influence of operation stop by unexpected black-out)

	Compared by normal operation	Critical shortage materials
Production Influence in May	Approximately Minus 15% As overall	<b>Wafer Fabrication:</b> Hydrogen peroxide, Epi wafers, Mixed Acid, etc <b>Assembly/Test</b> Diode chip, capacitors etc
Production Influence in June	Approximately Minus 20% As overall	<b>Wafer Fabrication:</b> Hydrogen peroxide, Epi wafers, Mixed Acid, etc <b>Assembly/Test</b> Diode chip, capacitors etc

We are making the best and every possible efforts to normalize our production as soon as possible. we can have the further information to inform you, we will inform you even partly. Thank you very much for your understanding.

Sincerely yours,



Yoshitsugu Tamakoshi  
General Manager  
Semiconductor & Device Marketing A.